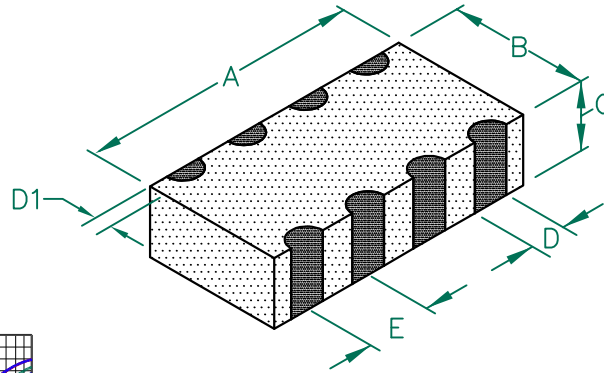


DA1206E300R-10

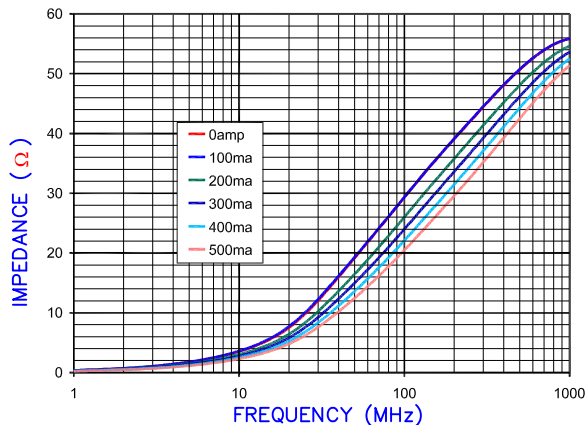
**UNCONTROLLED
DOCUMENT**

PHYSICAL DIMENSIONS:

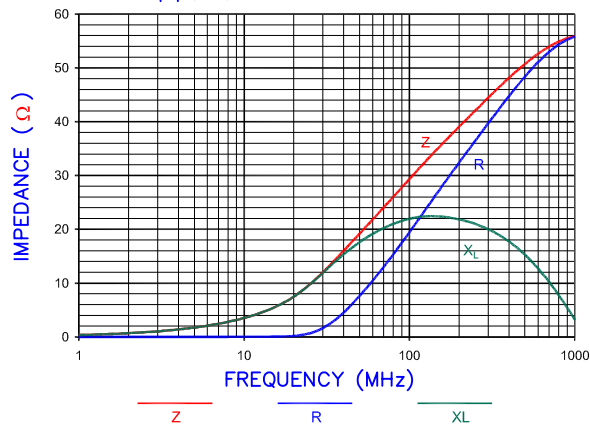
A	3.20 [.126]	± 0.20 [.008]
B	1.60 [.063]	± 0.20 [.008]
C	0.80 [.031]	± 0.20 [.008]
D	0.40 [.016]	± 0.15 [.006]
D1	0.30 [.012]	± 0.20 [.008]
E	0.80 [.031]	± 0.10 [.004]



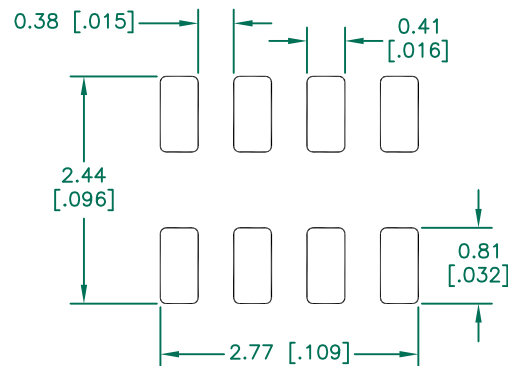
Z vs. FREQUENCY
IMPEDANCE UNDER DC BIAS



|Z|, R, AND XL vs. FREQUENCY



LAND PATTERNS FOR REFLOW SOLDERING



(For wave soldering, add 0.762 (0.030) to this dimension)

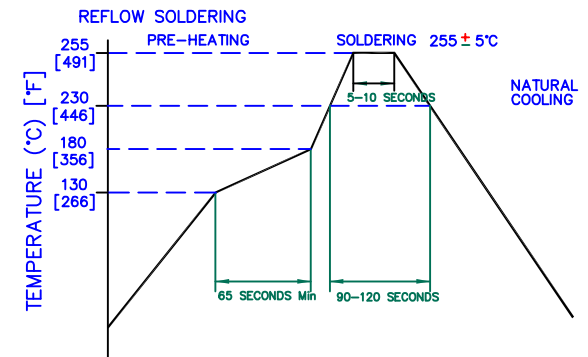
ELECTRICAL CHARACTERISTICS:

Z @ 100MHz (Ω)	DCR (Ω)	Rated Current
Nominal	30	
Minimum	23	
Maximum	38	0.3
500 mA		
LINE TO LINE INSULATION RESISTANCE >100 M Ω AT 75 VOLTS.		

NOTES: UNLESS OTHERWISE SPECIFIED

1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 3000 PCS/REEL.
2. TERMINATION FINISH IS 100% TIN.
3. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
4. OPERATING TEMPERATURE TEMP: $-40^{\circ}\text{C} \sim +125^{\circ}\text{C}$ (INCLUDING SELF-HEATING)

RECOMMENDED SOLDERING CONDITIONS



DIMENSIONS ARE IN mm [INCHES].				This print is the property of Laird Tech. and is loaned in confidence subject to return upon request and with the understanding that no copies shall be made without the written consent of Laird Tech. All rights to design or invention are reserved.			
D	OPERATING TEMPERATURE UPDATE LAIRD LOGO AND REFLOW CURVE	08/05/13	QU	PROJECT/PART NUMBER: DA1206E300R-10			
C	UPDATE COMPANY LOGO	05/22/09	JRK				
B	D1 dim chgd from 0.008 ± 0.004 to 0.012 ± 0.008. ADD ROHS, UPDATE COMPANY LOGO	10/31/07	JRK	DATE:	03/30/04	SCALE:	NTS
A	ORIGINAL DRAFT	03/30/04	TMB	CAD #	DA1206E300R-10-D	TOOL #	-
REV	DESCRIPTION	DATE	INT	SHEET: 2 of 2			